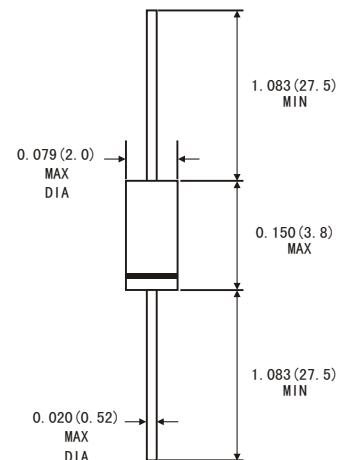


## FEATURES

- Metal-on-silicon junction
- Low turn-on voltage
- Ultrafast switching speed
- Primarily intended for high level UHF mixers and ultrafast switching applications
- The diode is also available in the MiniMELF case with type designation LL45.
- High temperature soldering guaranteed: 260°C/10 seconds at terminals

## DO-35



## MECHANICAL DATA

- Case: DO-35 glass case
- Polarity: color band denotes cathode end
- Weight: Approx. 0.13 gram

Dimensions in inches and (millimeters)

## ABSOLUTE RATINGS(LIMITING VALUES)

	Symbols	Value	Units
Peak Reverse Voltage	V <sub>RRM</sub>	15	V
Forward Continuous Current	I <sub>F</sub>	30	mA
Surge non repetitive forward current t <sub>p</sub> ≤ 1s	I <sub>FSM</sub>	60	mA
Junction and Storage temperature range	T <sub>TG</sub> T <sub>J</sub>	-65 to +150 -65 to +125	°C
Maximum Lead Temperature for Soldering during 10s at 4mm from Case	T <sub>L</sub>	230	°C

## ELECTRICAL CHARACTERISTICS

	Symbols	Min.	Typ.	Max.	Units
Reverse breakdown voltage at I <sub>R</sub> =10μA	V <sub>R</sub>	15			V
Leakage current at V <sub>R</sub> =6V	I <sub>R</sub>			100	nA
Forward voltage drop at I <sub>F</sub> =1mA Test pulse: t <sub>p</sub> ≤ 300μs δ < 2% I <sub>F</sub> =10mA I <sub>F</sub> =30mA	V <sub>F</sub>			0.38 0.50 1	V
Junction Capacitance at V <sub>R</sub> =1V, f=1MHz	C <sub>J</sub>			1.1	PF
Thermal resistance	R <sub>θJA</sub>			400	K/W



Figure 1. Forward current versus forward voltage at different temperatures(typical values)

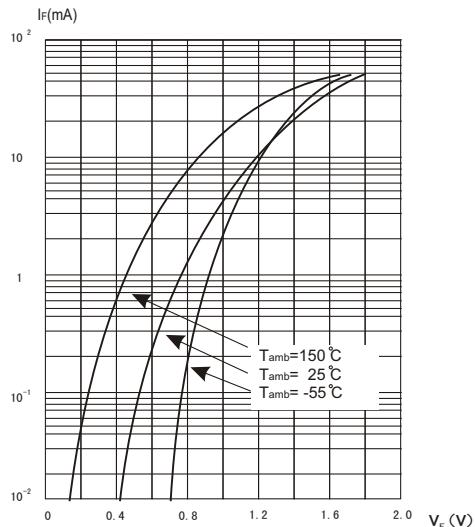


Figure 2 Capacitance  $C_J$  versus reverse applied voltage  $V_R$  (typical values)

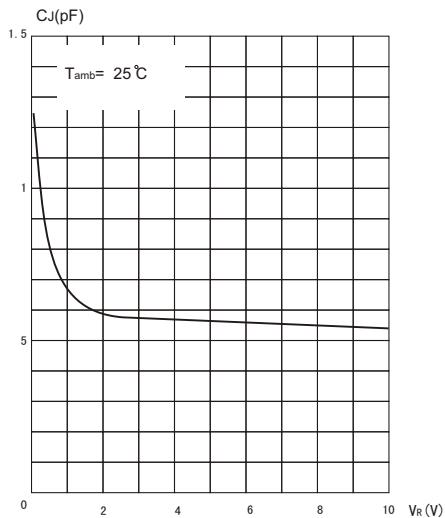


Figure 3.Reverse current versus ambient temperature

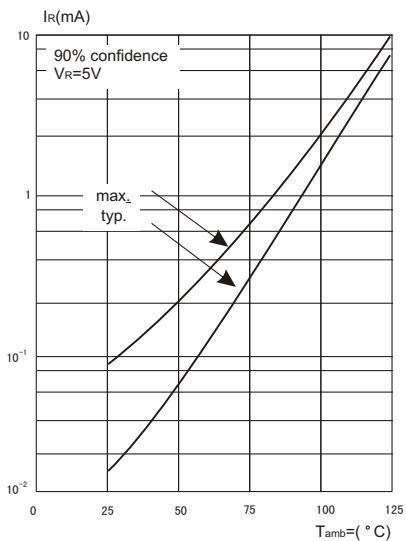


Figure 4.Reverse current versus continuous revers voltage (typical values)

